

Weidmüller Interface GmbH & Co. KG Klingenbergstraße 26 D-32758 Detmold Germany

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Product image





High-temperature-resistant, straight, open pin header. Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, Solder flange, THT/THR solder connection, 5.08 mm, Number of poles: 6, 270°, Solder pin length (I): 3.2 mm, tinned, black, Box
Order No.	<u>1877460000</u>
Туре	SL-SMT 5.08HC/06/270FH 3.2SN BK BX
GTIN (EAN)	4032248468089
Qty.	50 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

Creation date March 26, 2021 2:19:40 AM CET

Catalogue status 12.03.2021 / We reserve the right to make technical changes.



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Technical data

Depth	12 mm	Depth (inches)	0.472 inch
Height	14.2 mm	Height (inches)	0.559 inch
Height of lowest version	11 mm	Net weight	4.4 g
Width	40.28 mm	Width (inches)	1.586 inch

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	270°
Number of poles	6	Number of solder pins per pole	1
Solder pin length (I)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.4 mm
Solder eyelet hole diameter toler	rance (D)+ 0,1 mm	L1 in mm	25.4 mm
L1 in inches	1 inch	Number of rows	1
Pin series quantity	1	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	9 N
Pulling force/pole, max.	7 N		

Material data

Insulating material	LCP GF
Colour chart (similar)	RAL 9011
Comparative Tracking Index (CTI)	≥ 175
UL 94 flammability rating	V-0
Contact surface	
	tinned
Layer structure of plug contact	13 µm Ni / 24 µm Sn
	matt
Storage temperature, max.	70 °C
Operating temperature, max.	100 °C
Temperature range, installation, max.	100 °C

Colour	black
Insulating material group	Illa
Moisture Level (MSL)	1
Contact material	CuMg
Layer structure of solder connection	13 µm Ni / 24 µm Sn
	matt
Storage temperature, min.	
	-40 °C
Operating temperature, min.	-50 °C
Temperature range, installation, min.	-30 °C

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	27.5 A
Rated current, max. number of poles		Rated current, min. number of poles	
(Tu=20°C)	19 A	(Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2 4 kV		Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

Technical data

SL-SMT 5.08HC/06/270FH 3.2SN BK BX



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nstitute (CSA)		Certificate No. (CSA)	
	(SP*		
			200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	18.5 A	Rated current (Use group D / CSA)	18.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Rated data acc. to UL 1059			
nstitute (UR)		Certificate No. (UR)	
	R		
			E60693
Rated voltage (Use group B / UL 1059) Rated current (Use group B / UL 1059)	300 V 18.5 A	Rated voltage (Use group D / UL 1059) Rated current (Use group D / UL 1059)	
Reference to approval values	Specifications are	Rated current (Use group D / OL 1059)	10 A
	maximum values, details - see approval certificate.		
Packing			
Packaging	Box	VPE length	35 mm
/PE width	60 mm	VPE height	140 mm
Classifications			
ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
mportant note			
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properti in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.		
Notes	Gold-plated contact surfaces	on request	
	Rated current related to rated cross-section & min. No. of poles.		
	• Diameter of solder eyelet D = 1.4+0.1mm		
	• Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles		
	• P on drawing = pitch		
	 Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. 		
	-		



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Technical data

Approvals	
Approvals	
ROHS	Conform
UL File Number Search	E60693
Downloads	
Approval/Certificate/Document of	
Conformity	Declaration of the Manufacturer
Engineering Data	STEP





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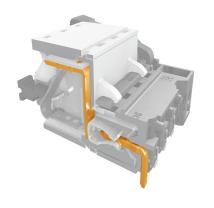
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Product imageDimensional drawingImage: Dimensional drawing</t

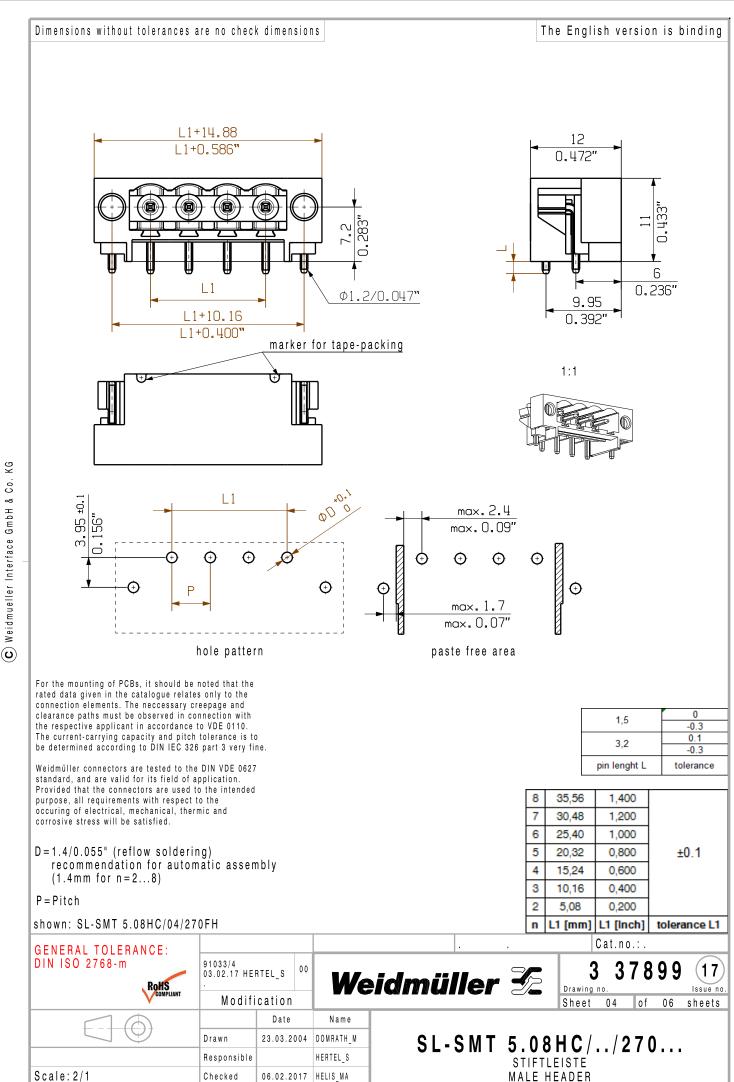
HOLE PATTERN

Product benefits



Safe power transmission Proven properties

Creation date March 26, 2021 2:19:40 AM CET



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Product file: SL-SMT 5.08

06.02.2017

Checked

Approved

Supersedes: .

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Wave Solder Profile

Recommended wave solderding profiles

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Double Wave:

Single Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile



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Time [sec]

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.